

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings of claims in the application:

Listing of Claims:

1-8. (Canceled)

9. (Currently amended): A sealing structure for multi-chip modules comprising:
a wiring board having one face mounted with a plurality of semiconductor devices and another face having connecting pins arranged thereover;
a first frame having a thermal expansion coefficient compatible with that of the wiring board, the first frame provided on a periphery of the face of the wiring board mounted with the semiconductor devices;
a second frame disposed over the first frame;
a cap having a circumference and having a thermal expansion coefficient different from that of the first and second frames and covering the plurality of semiconductor devices;
a heat conducting material disposed between the cap and the plurality of semiconductor devices for transmitting heat from the semiconductor devices to the cap;
an attachment to fix the first frame and the wiring board to each other;
a fastener for fastening the first and second frames and the cap together via an intervening member,
the cap being spaced apart from the first and second frames by the intervening member,
wherein there is an absence of any direct physical contact between the cap and either the first and second frames.

1 10. (Original): A sealing structure for multi-chip modules as in claim 9
2 wherein O ring grooves are provided in one face of the first frame and one face of the second
3 frame, and the cap is fastened between the first frame and the second frame using at least one O
4 ring.

1 11. (Original): A sealing structure for multi-chip modules as in claim 10
2 wherein an elastic member is provided between a side face of the cap and a face of the first
3 frame.

1 12. (Original): A sealing structure for multi-chip modules as in claim 9
2 wherein elastic packing is provided between the first frame and the second frame so as to cover
3 the circumference of the cap.